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(54) Title: FLEXIBLE CIRCUIT ON REFLECTIVE SUBSTRATE

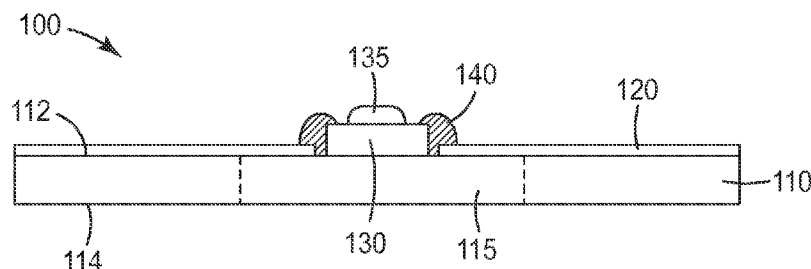


FIG. 1B

(57) Abstract: The present disclosure describes materials and methods for creating electrical circuits on a non-conductive multilayer reflector substrate that can withstand reflow temperatures with low temperature solder pastes without creating distortions in the reflective substrate. The materials and methods include the use of a novel reflective mirror film based on silicone polyoxamide polymers or copolymers, which can retain reflectivity at these temperatures without damage to reflection or other film properties.